

EAST Search History

S64	23815	S63 and ((dice dicing separation separat\$3 cutting cut\$2 dividing divid\$3 singularity single) near2 (line groove alignment adj mark))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/11/17 15:07
S65	61	S64 and ((laser near3 beam near irradiat\$3) near2 (line groove alignment adj mark))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/11/17 15:11
S66	12	S65 and ((laser near3 beam near irradiat\$3 line groove alignment adj mark) with (grind\$3 polish\$4 blast\$3))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/11/17 15:11
S67	623	((laser near3 beam near irradiat\$3) near2 (line groove alignment adj mark))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/11/17 15:11
S68	19	S67 and ((laser near3 beam near irradiat\$3 line groove alignment adj mark) with (grind\$3 polish\$4 blast\$3))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/11/17 15:11
S69	267261	(dice dicing separation separat\$3 cutting cut\$2 dividing divid\$3 singularity individual single) near5 (wafer substrate workpiece)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/11/17 15:41
S70	168	S69 and (dice dicing separation separat\$3 cutting cut\$2 dividing divid\$3 singularity individual single) near5 (mark line/groove void dicing line perforat\$3) near5 (laser near3 irradiat\$3)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/11/17 15:41
S71	37	S70 and (dice dicing separation separat\$3 cutting cut\$2 dividing divid\$3 singularity individual single) with (polish\$3 grind\$3)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/11/17 15:43
S12 3	12	"6294439"	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/11/18 12:05
S12 4	1	10/839430	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/11/18 12:06
S12 5	3	"6653698"	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/11/18 12:07
S12 6	473	438/33, 68,113-114,458,460-465. ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/07/12 18:25
S12 7	4916	438/33,68,113-114,458,460-465. ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/07/12 18:25

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S12 8	1563	S127 and laser	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/07/12 18:25
S12 9	1342	S128 and ((dice dicing separation separat\$3 cutting cut\$2 dividing divid\$3 singularity individual single) near5 (wafer substrate workpiece))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/07/12 18:26
S13 0	1075	S129 and ((dice dicing separation separat\$3 cutting cut\$2 dividing divid\$3 singularity individual single wafer substrate workpiece) with laser)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/07/12 18:27
S13 1	418	S129 and ((line groove) with laser)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/07/13 06:38
S13 2	1	10/601310	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/07/13 06:38
S13 3	1	"6558975".PN.	USPAT; USOCR	OR	OFF	2006/07/13 10:39
S13 4	1	"6500047".PN.	USPAT; USOCR	OR	OFF	2006/07/13 10:40
S13 5	1	"6293270".PN.	USPAT; USOCR	OR	OFF	2006/07/13 10:40
S13 6	1	"6083811".PN.	USPAT; USOCR	OR	OFF	2006/07/13 10:41
S13 7	1	"5888883".PN.	USPAT; USOCR	OR	OFF	2006/07/13 10:41
S13 8	1	"5369060".PN.	USPAT; USOCR	OR	OFF	2006/07/13 10:53
S13 9	1	"5219796".PN.	USPAT; USOCR	OR	OFF	2006/07/13 10:53